SensEye Imager/ADC
Chip-on-Board Mounting and Wirebonding Information

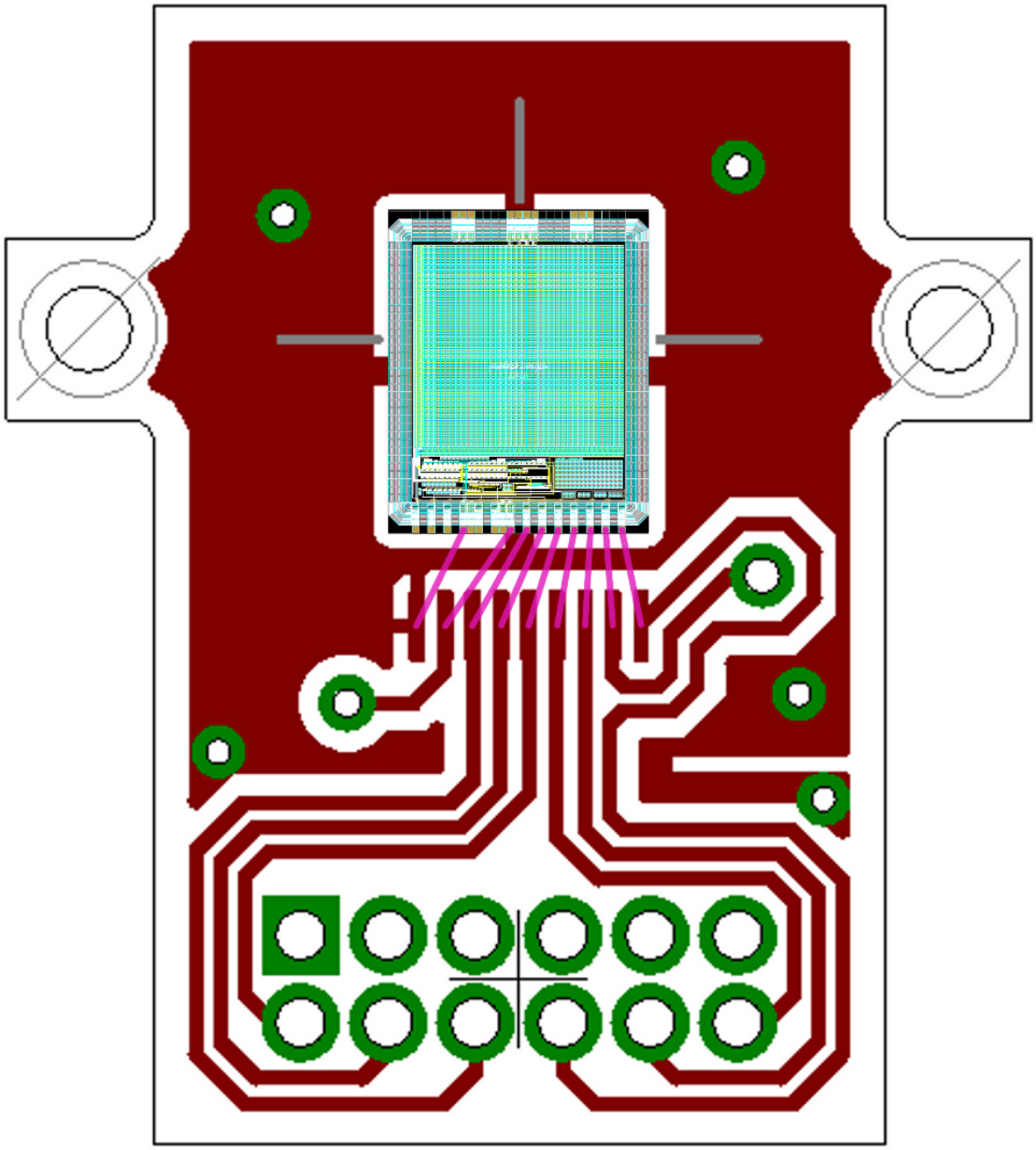

Figure 1: **SensEye Imager/ADC board wirebonding diagram.**

Figure 1 shows an image of the top layer of the two-layer SensEye Imager/ADC PCB with an image of the CentEye Stonyman die superimposed. This image indicates the orientation of the die on the board, as well as where the wirebonds are necessary to attach the die pads to the PCB board pads. The pad beneath the die is connected to GND, and conductive die attach is preferred, but not absolutely required.

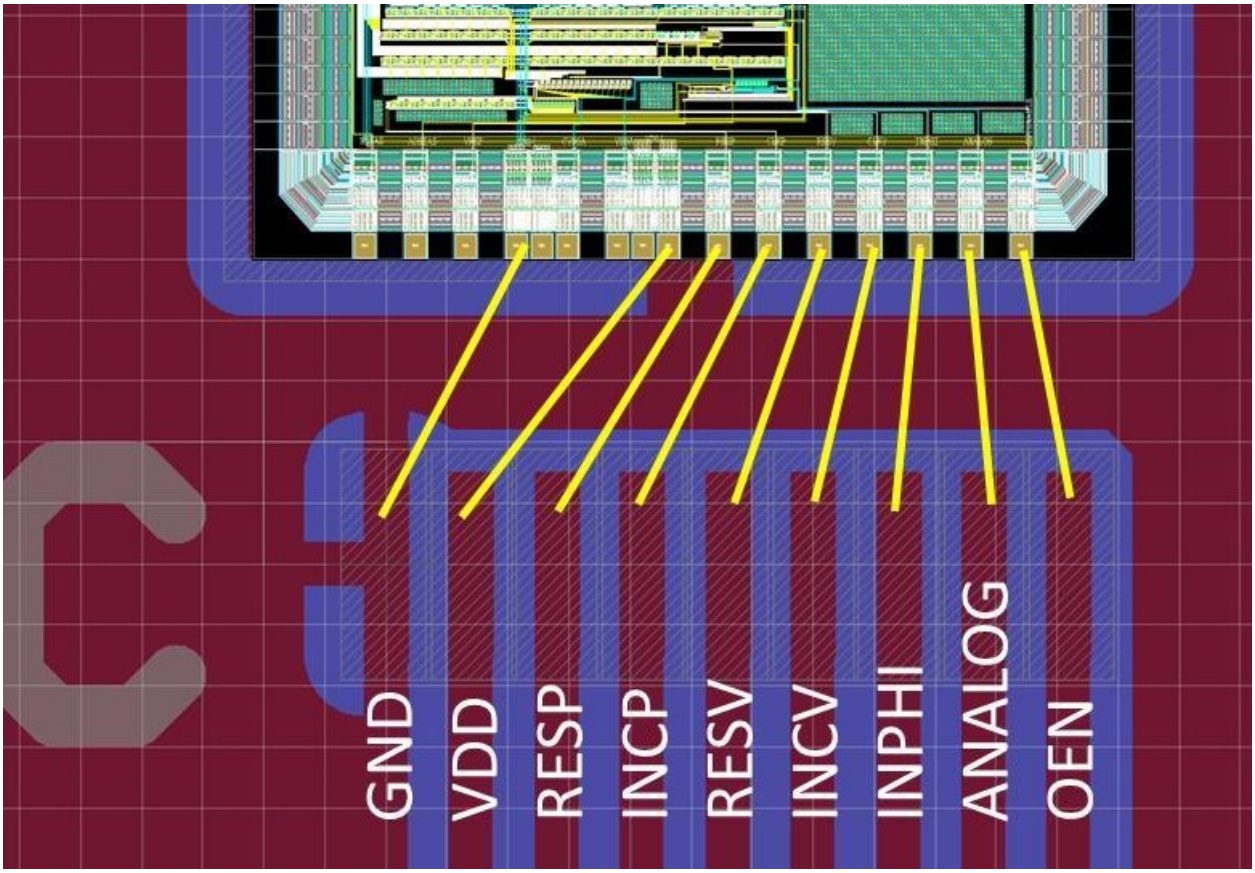

Figure 2: **Closeup wirebonding diagram.**

Figure 2 shows a closeup image of the wirebonding connects required to connect the Stonyman die pads to the PCB board pads. Nine wirebonds are required, as labelled: GND, VDD, RESP, INCP, RESV, INCV, INPHI, ANALOG and OEN.

Board pad pitch	0.016 inch
Board pad width	0.008 inch
Board pad height	0.039 inch

Table 1: **PCB board wirebonding pad attributes table.**

Die pad pitch (without spacers)	0.016 inch
Die pad pitch (with spacers)	0.016 inch
Die pad width	0.008 inch
Die pad height	0.039 inch

Table 2: **Stonyman die pad attributes table.**